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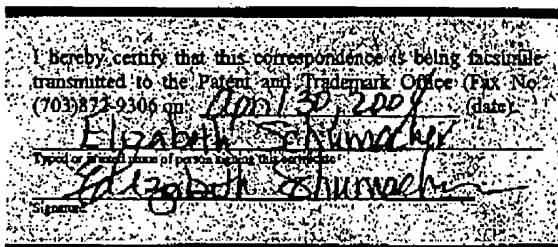
DOCKET NO. KHASELEV 1-1-7

OFFICIAL PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Khaselev, O.
Serial No.: 10/050,013
Filed: January 17, 2002
Title: Electroplating solution for high speed plating of tin-copper solder
Grp./A.U.: 1753
Examiner: Edna Wong

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450



Sir:

AMENDMENT UNDER 37 C.F.R. § 1.116

In response to the Examiner's Action mailed March 8, 2004, please accept the following amendments and remarks.

Ok to enter. CW 6/17/04